

## Japan Packaging Committee Meeting Summary and Minutes

### SEMI Japan Standards Summer 2013 Meetings

Friday, July 19, 2013, 15:00-17:00  
SEMI Japan, Tokyo, Japan

#### Next Committee Meeting

SEMI Japan Standards Fall 2013 Meetings  
Monday, November 11, 2013, 15:00-17:00  
SEMI Japan, Tokyo, Japan

#### Table 1 Meeting Attendees

**Co-Chairs:** Kazunori Kato (AiT), Masahiro Tsuruya (iNEMI)

**SEMI Staff:** Naoko Tejima (SEMI Japan)

<i>Company</i>	<i>Last</i>	<i>First</i>	<i>Company</i>	<i>Last</i>	<i>First</i>
Tokyo Seimitsu	Chiba	Kiyotaka	Elpida Memory	Sonobe	Kaoru
Fujitsu Semiconductor	Hayasaka	Noboru	Shin-Etsu Polymer	Tanaka	Kiyofumi
AiT	Kato	Kazunori	iNEMI	Tsuruya	Masahiro
Disco	Masuchi	Sumio	Corning	Kuniaki	Yamazaki
Canon Anelva	Matsuki	Nobuo	Hitachi High Technologies	Yoshino	Eiji
Lintec	Murakami	Yukinori	Lintec	Watanabe	Kenichi
AIST	Shimamoto	Haruo	SEMI Japan	Tejima	Naoko

\* alphabetical order by last name

#### Table 2 Leadership Changes

<i>Group</i>	<i>Previous Leader</i>	<i>New Leader</i>
JA 450mm Assembly and Test Die Preparation Task Force	Kinya Mochida (Lintec)	Kenichi Watanabe (Lintec)

#### Table 3 Ballot Results

**Passed** ballots and line items will be forwarded to the ISC Audit & Review Subcommittee for procedural review.

**Failed** ballots and line items were returned to the originating task forces for re-work and re-balloting.

<i>Document #</i>	<i>Document Title</i>	<i>Committee Action</i>
G92-0412	Rerated Information of G92-0412, Specification for Tape Frame Cassette for 450 mm Wafer	<b>Passed</b>

#### Table 4 Authorized Ballots

<i>#</i>	<i>When</i>	<i>SC/TF/WG</i>	<i>Details</i>
5637	Cycle 6, 2013	JA 450mm Assembly and Test Die Preparation Task Force	Revision of SEMI G95-0613, Mechanical Interface Specification for 450mm Load Port for Tape Frame Cassettes in the Backend Process

**Table 5 Authorized Activities**

#	Type	SC/TF/WG	Details
5636	SNARF	JA 450mm Assembly and Test Die Preparation Task Force	Revision of SEMI G92-0412, Specification for Tape Frame Cassette for 450mm Wafer
5637	SNARF	JA 450mm Assembly and Test Die Preparation Task Force	Revision of SEMI G95-0613, Mechanical Interface Specification for 450mm Load Port for Tape Frame Cassettes in the Backend Process
--	Revised TFOF	JA 450mm Assembly and Test Die Preparation Task Force	Revision of Scope. Add "About a method to align in Packaging Process of 450mm Notch-Free Wafer"

**Table 6 New Action Items (or move to Section 8, Action Item Review)**

Item #	Assigned to	Details
PKG120829-2	Committee Co-Chairs	To review the Committee Charter of Japan Packaging Committee
PKG120829-3	All Task Force Leaders	To review the both TFOF (Charter, Scope and Members) and SNARFs (Rationale and Scope) which they themselves are involved
PKG130325-2	3D-IC Study Group	To discuss the contents of SJ2013 Pavilion and Workshop with SEMI Staff
PKG130325-3	SEMI staff	To publish G92 Related Information
PKG130719-1	SEMI staff	To correct the previous meeting minutes.
PKG130719-2	SEMI staff	To request the NA 3DS-IC Committee to return comments to reject-voters of Doc.#5588.
PKG130719-3	SEMI staff	To forward the adjudication result of Related Information of SEMI G92-0412 to the ISC A&R Subcommittee for procedural review
PKG130719-4	450mm ATDP Task Force	To submit Doc.#5637 (G95) for Cycle 6, 2013.
PKG130719-5	SEMI staff	To collect the TF report from the co-leaders for this time record and to ask to submit the TF report for each meeting if no one will not attend the meeting.
PKG130719-6	SEMI staff	To check whether there are some documents for 5-year-review procedure.
PKG130719-7	SEMI staff	To provide some information about 450mm Notch-Free Wafer at SEMICON West, if any.
PKG130719-8	SEMI staff	To send the result of the questionnaire about 450mm Notch-Free which was implemented in June.
PKG130719-9	Co-chairs	To review all SNARFs and check whether they are written in the right way.

## 1 Welcome, Reminders and Introductions

Masahiro Tsuruya, committee co-chair, called the meeting to order at 15:00. Self-introductions were made followed by the agenda review.

## 2 Required Meeting Elements

The meeting reminders on program membership requirement, antitrust issues, intellectual property issues and international effective meeting guidelines, were reviewed by SEMI staff, Naoko Tejima.

### 3 Review of Previous Meeting Minutes

The committee reviewed the minutes of the previous meeting held on March 25, 2013.

**Motion:** To approve the minutes of the previous meeting as written on the condition of being corrected the below points.

**By / 2<sup>nd</sup>:** Kazunori Kato (AiT) / Kaoru Sonobe (Elpida Memory)

**Discussion:** The following points were as pointed;

- To delete one of co-leaders Thin Chip Die Bending Strength Measurement Method Task Force (Yuzo Shimobeppu, Fujitsu Semiconductor)
- To add the description that it will be gone through re-procedure at the next committee meeting, since the procedure was incomplete.

**Vote:** 12 in favor and 0 opposed. **Motion passed.**

**Action Item:** SEMI staff to correct the above points of the previous meeting minutes.

**Attachment:** 01\_JA\_Packaging\_Previous\_Mtg\_Minutes\_130719

### 4 SEMI Staff Report

Naoko Tejima gave the SEMI staff report. This report included SEMI Global 2013 Calendar of Events, Global Standards Meeting Schedule, NA Standards Meetings in conjunction with SEMICON West, 2013 Critical Dates for SEMI Standards Ballots, SEMI Standards Publication, SEMICON Japan 2013 Information and Contact Information.

**Attachment:** 02\_SEMI\_Staff\_Report\_130719

### 5 Liaison Reports

#### 5.1 North America 3DS-IC Committee Report

Naoko Tejima briefly reported for the North America 3DS-IC Committee. This report included Leadership, Organization Chart, Task Force Overview, SNARFs, Document Review Summary, Meeting Information, NA 3DS-IC Ballots and NA 3DS-IC Fall 2013 Meeting Schedule.

Some of JA 3D-IC Study Group (SG) members voted to reject for Document #5588, "Line Item Revisions to SEMI 3D2-0113, Specification for Glass Carrier Wafers for 3DS-IC Applications", however, it was passed committee review at NA 3DS-IC Committee meeting without any feedbacks to the reject-voters. JA 3D-IC SG members wanted NA 3DS-IC Committee to return some comments to their negatives before the committee review, even if it is not defined by the Regulations. JA 3D-IC SG members would like to request NA 3DS-IC Committee to return some comment to reject-voters.

**Action Item:** SEMI staff to request the NA 3DS-IC Committee to return comments to reject-voters.

**Attachment:** 03\_NA\_3DS-IC\_Comm\_Report\_13719

#### 5.2 Taiwan 3DS-IC Committee Report

Naoko Tejima briefly reported for the Taiwan 3DS-IC Committee. This report included Organization Chart, Task Force Overview, SNARFs, Meeting Information, Recently Available Taiwan 3DS-IC Ballots and Issued Taiwan 3DS-IC Ballots.

**Attachment:** 04\_TW\_3DS-IC\_Comm\_Report\_130719

### 6 Task Force Reports

#### 6.1 Electromagnetic Characterization Study Group

No report was provided by the Task Force.

#### 6.2 Packages and Packaging Materials Eco-efficiency Task Force

No report was provided by the Task Force.

### 6.3 Wafer Shipping Container for Assembly & Packaging Task Force

No report was provided by the Task Force.

### 6.4 DFM Study Group

No report was provided by the Task Force.

### 6.5 450mm Japan Assembly & Test Die Preparation Task Force

Sumio Masuchi reported on progress for Japan Assembly & Test Die Preparation Task Force.

#### 6.5.1 Approval of Related Information of SEMI G92-0412

The Related Information of SEMI G92-0412, Specification for Tape Frame Cassette for 450mm Wafer was presented to the committee for approval.

This document was reviewed and approved at the previous committee meeting. However, since the procedure was incomplete, it was gone through re-procedure.

**Action Item:** SEMI staff to forward the adjudication result of Related Information of SEMI G92-0412 to the ISC A&R Subcommittee for procedural review.

**Attachment:** 05\_Procedural Review for G92 RI\_130719

#### 6.5.2 Approval of a New SNARF for “Revision of SEMI G92-0412” (numbered Doec.#5636)

A new SNARF “Revision of SEMI G92-0412, Specification for Tape Frame Cassette for 450mm Wafer” was presented to the committee for approval.

**Motion:** To approve a new SNARF for “Revision of SEMI G92-0412, Specification for Tape Frame Cassette for 450mm Wafer”

**By / 2<sup>nd</sup>:** Sumio Masuchi (Disco) / Kenichi Watanabe (Lintec)

**Discussion:** None

**Vote:** 11 in favor and 0 opposed. **Motion passed.**

**Attachment:** 06\_G92\_Rev\_SNARF\_130719

#### 6.5.3 Approval of a New SNARF for “Revision of SEMI G95-0613” (numbered Doec.#5637)

A new SNARF “Revision of SEMI G95-0613, Mechanical Interface Specification for 450mm Load Port for Tape Frame Cassettes in the Backend Process” was presented to the committee for approval.

**Motion:** To approve a new SNARF for “Revision of SEMI G95-0613, Mechanical Interface Specification for 450mm Load Port for Tape Frame Cassettes in the Backend Process”

**By / 2<sup>nd</sup>:** Sumio Masuchi (Disco) / Kenichi Watanabe (Lintec)

**Discussion:** None

**Vote:** 11 in favor and 0 opposed. **Motion passed.**

**Attachment:** 07\_G95\_SNARF\_130719

#### 6.5.4 Approval of the Submission of Doc.#5637 “Revision of SEMI G95-0613” for Cycle 6, 2013

TF is drafting the document of Doc.#5637, “Revision of SEMI G95-0613, Mechanical Interface Specification for 450mm Load Port for Tape Frame Cassettes in the Backend Process” and it will be submitted for Cycle 6, 2013. It was presented to the committee for approval.

**Motion:** To submit Doc.#5637 for Cycle 6, 2013.

**By / 2<sup>nd</sup>:** Sumio Masuchi (Disco) / Kenichi Watanabe (Lintec)

**Discussion:** None.

**Vote:** 11 in favor and 0 opposed. **Motion passed.**

**Action Item:** 450mm ATDP Task Force to submit Doc.#5637 for Cycle 6, 2013.

#### 6.5.5 Revision of TFOF

Adding “the method to align in Packaging Process of 450mm Notch-Free Wafer” to the Scope of TFOF was proposed.

**Motion:** To approve a revised TFOF of Japan 450mm Assembly & Test Die Preparation Task Force

**By / 2<sup>nd</sup>:** Sumio Masuchi (Disco) / Kenichi Watanabe (Lintec)

**Discussion:** None

**Vote:** 10 in favor and 0 opposed. **Motion passed.**

**Attachment:** 08\_STDP\_Rev\_TFOF\_130719

#### 6.5.6 Leader ship

Kinya Mochida (Lintec) stepped down as a co-leader of the Japan 450mm Assembly & Test Die Preparation TF. Kenichi Watanabe (Lintec) has been appointed as a new co-leader.

#### 6.6 Thin Chip Die Bending Strength Measurement Method Task Force

Haruo Shimamoto reported on progress for the Thin Chip Die Bending Strength Measurement Method Task Force.

**Attachment:** 09\_ThinChipDieBending\_TF\_Report\_130719

#### 6.7 3D-IC Study Group

Masahiro Tsuruya reported on progress for the 3D-IC Study Group.

**Attachment:** 10\_3D-IC\_SG\_Report\_130719

## 7 Old Business

### 7.1 Previous Meeting Action Items

Naoko Tejima reviewed the previous meeting action items.

**Table 7 Previous Meeting Actions Items**

<i>Item #</i>	<i>Assigned to</i>	<i>Details</i>
PKG120829-2	Committee Co-Chairs	To review the Committee Charter of Japan Packaging Committee <b>Open</b>
PKG120829-3	All Task Force Leaders	To review the both TFOF (Charter, Scope and Members) and SNARFs (Rationale and Scope) which they themselves are involved <b>Open</b>
PKG130325-1	SEMI	To forward adjudication result of Doc.4965C to the ISC A&R Subcommittee for procedural review. <b>Closed</b>
PKG130325-2	3D-IC Study Group	To discuss the contents of SJ2013 Pavilion and Workshop with SEMI Staff <b>Open</b>
PKG130325-3	SEMI	To publish G92 Related Information <b>Open</b>

## 8 New Business

None

## 9 Action Item Review

### 9.1 New Action Items

Naoko Tejima reviewed the new action items. These can be found in the New Action Items table at the beginning of these minutes.

## 10 Next Meeting and Adjournment

The next meeting of the Japan Packaging Committee is scheduled for Monday, November 11, 2013, 15:00-17:00, at SEMI Japan, Tokyo, Japan.



Respectfully submitted by:  
Naoko Tejima  
Manager, Standards  
SEMI Japan  
Phone: +81.3.3222.5804  
Email: ntejima@semi.org

Minutes approved by:

Kazunori Kato (AiT), Co-chair	August 10, 2013
Masahiro Tsuriya (iNEMI), Co-chair	August 10 , 2013

**Table 8 Index of Available Attachments #1**

#	<i>Title</i>
1	JA_PKG_Previous_Mtg_Minutes_130719
2	SEMI_Staff_Report_130719
3	NA_3DS-IC_Comm_Report_130719
4	TW_3DS-IC_Comm_Report_130719
5	Procedural_Review_for_G92_RI_130719
6	G92_Rev_SNARF_130719
7	G95_Rev_SNARF_130719
8	ATDP_Rev_TFOF_130719
9	ThinChipDieBending_TF_Report_130719
10	3D-IC_SG_Report_130719

#1 Due to file size and delivery issues, attachments must be downloaded separately. A .zip file containing all attachments for these minutes is available at [www.semi.org](http://www.semi.org). For additional information or to obtain individual attachments, please contact Naoko Tejima at the contact information above.